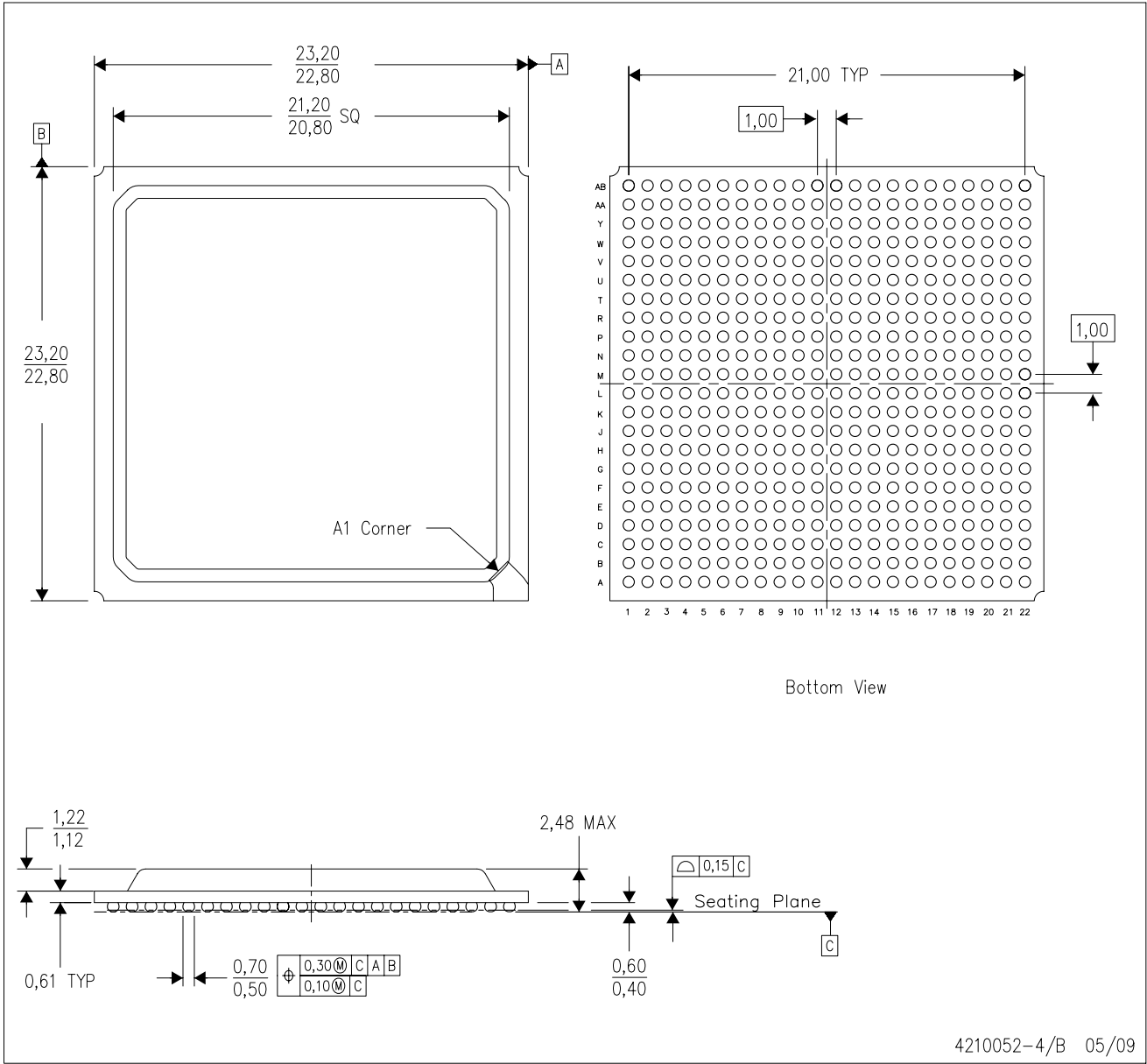


ZHR (S-PBGA-N484)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MO-151
 - D. Thermally Improved BGA (TI-BGA).
 - E. Soldermask under die is opened
 - F. This is a Pb-free solder ball design.

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